

WWW.100Y.COM.TW **Data Sheet**

WWW.100Y.COM.TW **SST 29VE010** 2.7V-only 1 Megabit Page Mode EEPROM

WWW.100Y.COM.

力 材 料 886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787 Http://www. 100y. com. tw

WWW.101

WWW.100Y.COM

WWW.100Y.COM.

July 1996

WWW.100Y.COM.TW



勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787 Http://www.100y.com.tw

Features:

Single 2.7-Volt Read and Write Operations CMOS SuperFlash EEPROM Technology

Endurance: 100,000 Cycles (typical) Greater than 100 years Data Retention

Low Power Consumption:

Active Current: 10 mA (typical) Standby Current: 10 µA (typical)

Fast Page-Write Operation

128 Bytes per Page, 1024 Pages

Page-Write Cycle: 5 ms (typical)
Complete Memory Rewrite: 5 sec (typical)
Effective Byte-write Cycle Time:39 µs (typical)

Fast Access Time: 200 and 250 ns

Latched Address and Data
Automatic Write Timing with Internal
V_{pp} Generation
End of Write Detection

Toggle Bit Data# Polling

Hardware and Software Data Protection
TTL I/O Compatibility
JEDEC Standard Byte-wide EEPROM
Pinouts

Packages Available

32-Pin TSOP 32-Lead PLCC 32 Pin Plastic DIP

Product Description

The 29VE010 is a 128K x 8 CMOS page mode EEPROM manufactured with SST's proprietary, high performance CMOS SuperFlash technology. The split gate cell design and thick oxide tunneling injector attain better reliability and manufacturability compared with alternate approaches. The 29VE010 writes with a 2.7-volt-only power supply. (V_{CC} : 2.7V to 3.6V) Internal erase/program is transparent to the user. The 29VE010 conforms to JEDEC standard pinouts for byte-wide memories.

Featuring high performance page write, the 29VE010 provides a typical byte-write time of 39 µsec. The entire memory, i.e., 128K bytes, can be written page by page in as little as 5 seconds, when using interface features such as Toggle Bit or Data# Polling to indicate the completion of a write cycle. To protect against inadvertent write, the 29VE010 has on-chip hardware and software data protection schemes. Designed, manufactured, and tested for a wide spectrum of applications, the 29VE010 is offered with a guaranteed page-write endurance of 10 or 10 cycles. Data retention is rated at greater than 100 years.

The 29VE010 is suited for applications that require convenient and economical updating of program, configuration, or data memory. For all system applications, the 29VE010 significantly improves performance and reliability, while lowering power consumption, when compared with 5volt EEPROM or EPROM approaches. The 29VE010

improves flexibility while lowering the cost for pogram, data, and configuration storage applications.

To meet high density, surface mount requiements, the 29VE010 is offered in 32-pin TSOP and 32-lead PLCC packages. A 600-mil, 32-pin PDIP package is also available. See Figures 2A and 2B for pinouts.

Device Operation

The SST page mode EEPROM offers in-circuit electrical write capability. The 29VE010 does not require separate erase and program operations. The internally timed write cycle executes both erase and program transparently to the user. The 29VE010 has industry standard optional Software Data Protection, which SST recommends always to be enabled. The 29VE010 is compatible with industry standard EEPROM pinouts and furctionality.

Read

The read operation of the 29VE010 is controlled by CE# and OE#, both have to be low for the system to obtain data from the outputs. CE# is used for device selection. When CE# is high, the chip is deselected and only standby power is consumed. OE# is the output control and is used to gate data from the output pins. The data bus is in high impedance state when either CE# or OE# is high. Refer to the read cycle timing diagram for further details (Figure 3).

勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787 Http://www.100y.com.tw

SST 29VE010 2.7V-only 1 Megabit Page Mode EEPROM



Write

The write operation consists of three steps. The first step is the optional three byte load sequence for Software Data Protection. This is an optional first step in the write operation, but highly recommended to ensure proper data integrity. Step 2 is the byte-load cycle to a page buffer of the 29VE010. Step 3 is an internally controlled write cycle for writing the data loaded in the page buffer into the memory array for nonvolatile storage. During the byte-load cycle, the addresses are latched by the falling edge of either CE# or WE#, whichever occurs last. The data is latched by the rising edge of either CE# or WE#, whichever occurs first. The internal write cycle is initiated by a timer after the rising edge of WE# or CE#, whichever occurs first. The write cycle, once initiated, will continue to completion, typically within 5 ms. See Figures 4 and 5 for WE# and CE# controlled page write cycle timing diagrams and Figures 15 and 17 for flowcharts.

The write operation has three functional cycles: the optional Software Data Protection load sequence, the page load cycle and the internal write cycle. The Software Data Protection consists of a specific three byte load sequence that will leave the 29VE010 protected at the end of the page write. The page load cycle consists of loading 1 to 128 bytes of data into the page buffer. The internal write cycle consists of the T_{BLCO} time-out and the write timer operation. During the write opeation, the only valid reads are Data# Polling and Toggle Bit.

The page-write operation allows the loading of up to 128 bytes of data into the page buffer of the 29VE010 before the initiation of the internal write cycle. During the internal write cycle, all the data in the page buffer is written simultaneously into the memory array. Hence, the page-write feature of 29VE010 allows the entire memory to be written in as little as 5 seconds. During the internal write cycle, the host is free to perform additional tasks, such as to fetch data from other locations in the system to set up the write to the next page. In each page-write operation, all the bytes that are loaded into the page buffer must have the same page address, i.e., A through A₁₆. Any byte not loaded with user data will be written to FF.

See Figures 4, 5, and 8 for the page-write cycle timing diagrams. If after the initial byte-load cycle. the host loads a second byte into the page buffer within a byte-load cycle time (T_{BLC}) of 100 μ s, the 29VE010 will stay in the page load cycle. Addtional bytes are then loaded consecutively. The page load cycle will be terminated if no additional byte is loaded into the page buffer within 200 µs (T_{BLCO}) from the last byte-load cycle, i.e., no subsequent WE# or CE# high-to-low transition after the last rising edge of WE# or CE#. Data in the page buffer can be changed by a subsequent byte-load cycle. The page load period can continue indefinitely, as long as the host continues to load the device within the byte-load cycle time of 100 µs. The page to be loaded is determined by the page address of the last byte loaded.

Software Chip-Erase

The 29VE010 provides a chip-erase operation, which allows the user to simultaneously clear the entire memory array to the "1" state. This is useful when the entire device must be quickly erased.

The Software Chip-Erase operation is initiated by using a specific six byte-load sequence. After the load sequence, the device enters into an internally timed cycle similar to the write cycle. During the erase operation, the only valid read is Toggle Bit. See Table 4 for the load sequence, Figure 10 for timing diagram, and Figure 19 for the flowchart.

Write Operation Status Detection

The 29VE010 provides two software means to detect the completion of a write cycle, in order to optimize the system write cycle time. The sofware detection includes two status bits: Data# Polling (DQ $_7$) and Toggle Bit (DQ $_6$). The end of write detection mode is enabled after the rising WE# or CE# whichever occurs first, which initiates the internal write cycle.

The actual completion of the nonvolatile write is asynchronous with the system; therefore, either a Data# Polling or Toggle Bit read may be simulaneous with the completion of the write cycle. If this occurs, the system may possibly get an eroneous result, i.e., valid data may appear to conflict with either DQ_7 or DQ_6 . In order to prevent spuious rejection, if an erroneous result occurs, the software routine should include a loop to read the



accessed location an additional two (2) times. If both reads are valid, then the device has completed the write cycle, otherwise the rejection is valid.

Data# Polling (DQ7)

When the 29VE010 is in the internal write cycle, any attempt to read DQ_r of the last byte loaded during the byte-load cycle will receive the complement of the true data. Once the write cycle is completed, DQ_r will show true data. The device is then ready for the next operation. See Figure 6 for Data# Polling timing diagram and Figure 16 for a flowchart.

Toggle Bit (DQ₆)

During the internal write cycle, any consecutive attempts to read DQ_δ will produce alternating 0's and 1's, i.e., toggling between 0 and 1. When the write cycle is completed, the toggling will stop. The device is then ready for the next operation. See Figure 7 for Toggle Bit timing diagram and Figure 16 for a flowchart. The read of the Toggle Bit will be a "1".

Data Protection

The 29VE010 provides both hardware and sofware features to protect nonvolatile data from inadvertent writes.

Hardware Data Protection

Noise/Glitch Protection: A WE# or CE# pulse of less than 5 ns will not initiate a write cycle.

 \underline{V}_{CC} Power Up/Down Detection The write operation is inhibited when V_{CC} is less than 2.5V.

Write Inhibit Mode: Forcing OE# low, CE# high, or WE# high will inhibit the write operation. This pevents inadvertent writes during power-up or power-down.

勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787 Http://www.100y.com.tw

Software Data Protection (SDP)

The 29VE010 provides the JEDEC approved φ-tional software data protection scheme for all data alteration operations, i.e., write and chip erase. With this scheme, any write operation requires the inclusion of a series of three byte-load operations to precede the data loading operation. The three byte-load sequence is used to initiate the write cycle, providing optimal protection from inadvetent write operations, e.g., during the system power-up or power-down. The 29VE010 is shipped with the software data protection disabled.

The software protection scheme can be enabled by applying a three-byte sequence to the device, during a page-load cycle (Figure 8). The device will then be automatically set into the data protect mode. Any subsequent write operation will require the preceding three-byte sequence. See Table 4 for the specific software command codes and Figure 8 for the timing diagram. To set the device into the unprotected mode, a six-byte sequence is required. See Table 4 for the specific codes and Figure 9 for the timing diagram. If a write is attempted while SDP is enabled the device will be in a non-accessible state for ~ 300 µs. SST recommends Software Data Protection always be enabled. See Figure 17 for flowcharts.

The 29VE010 Software Data Protection is a global command, protecting (or unprotecting) all pages in the entire memory array once enabled (or disabled). Therefore using SDP for a single page write will enable SDP for the entire array. Single pages by themselves cannot be SDP enabled or disabled.

Single power supply reprogrammable nonvolatile memories may be unintentionally altered. SST strongly recommends that Software Data Protection (SDP) always be enabled. The 29VE010 should be programmed using the SDP command sequence. SST recommends the SDP Disable Command Sequence not be issued to the device prior to writing.



Product Identification

The product identification mode identifies the device as the 29VE010 and manufacturer as SST. This mode may be accessed by hardware or software operations. The hardware operation is typically used by a programmer to identify the corect algorithm for the 29VE010. Users may wish to use the software product identification opeation to identify the part (i.e., using the device code) when using multiple manufacturers in the same socket. For details, see Table 3 for hadware operation or Table 4 for software operation, Figure 11 for the software ID entry and read timing diagram and Figure 18 for the ID entry command sequence flowchart. The manufacturer and device codes are the same for both opeations.

Table 1: Product Identification Table

W. 100 F. CON	Byte	Data
Manufacturers Code	0000 H	BF H
Device Code	0001 H	07 H

Product Identification Mode Exit

In order to return to the standard read mode, the Software Product Identification mode must be α -ited. Exiting is accomplished by issuing the Software ID Exit (reset) operation, which returns the device to the read operation. The reset opeation may also be used to reset the device to the read mode after an inadvertent transient condition that apparently causes the device to behave abnormally, e.g., not read correctly. See Table 4 for software command codes, Figure 12 for timing waveform and Figure 18 for a flowchart.

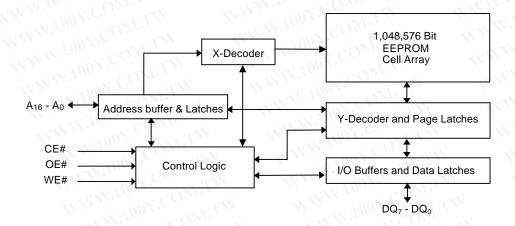


Figure 1: Functional Block Diagram of SST 29VE010





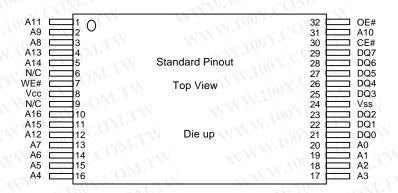
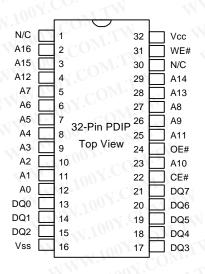


Figure 1A: Pin Assignments for 32-pin TSOP Pac kages



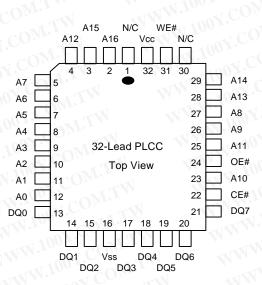


Figure 2B: Pin Assignments for 32-pin Plastic DIPs and 32-lead PLCCs



Table 2: Pin Description

Symb	ol Pin Name	Functions
A ₁₆ -A ₇	Row Address Inputs	To provide memory addresses. Row addresses define a page for a write cycle.
A_6-A_0	Column Address Inputs	Column Addresses are toggled to load page data.
DQ ₇ -D	Q ₀ Data Input/output	To output data during read cycles and receive input data during write cycles. Data is internally latched during a write cycle. The outputs are in tri-state when OE# or CE# is high.
CE#	Chip Enable	To activate the device when CE# is low.
OE#	Output Enable	To gate the data output buffers.
WE#	Write Enable	To control the write operations
Vcc	Power Supply	To provide 3.0-volt supply (2.7 - 3.6V)
Vss	Ground	1001. COW. I.A. M. A. M. 100 COW. I.A.
NC	No Connection	Unconnected pins.

Table 3: Operation Modes Selection

Mode	CE#	OE#	WE#	DQ	Address
Read	V _{IL}	V _{IL}	V _{IH}	D _{OUT}	A _{IN}
Page Write	V_{IL}	V_{IH}	V_{IL}	D _{IN}	A _{IN}
Standby	V_{IH}	Χ	X	High Z	X VVVV 100Y.
Write Inhibit	X	V_{IL}	X	High Z/ D _{OUT}	X WWW.
Write Inhibit	X	X	V_{IH}	High Z/ D _{OUT}	X WWW.TO COM
Software Chip Erase	VIL	V_{IH}	V_{IL}	D _{IN}	A _{IN} , See Table 4
Product Identification	- 1 T	W	W	TI 100Y.CO.TI.TY	WW. 1007.
Hardware Mode	V _{IL}	V_{IL}	V _{IH}	Manufacturer Code (BF)	$A_{16} - A_1 = V_{IL}, A_9 = V_H, A_0 = V_{IL}$
	COM.	\ \ \ \ - \		Device Code (07)	$A_{16} - A_1 = V_{IL}, A_9 = V_H, A_0 = V_{IH}$
Software Mode	VIL	V_{IH}	V _{IL}	MAN TOO YOUNG THE	See Table 4
SDP Enable Mode	V _{IL}	V _{IH}	V _{IL}	WW TIOOY.COM.T	See Table 4
SDP Disable Mode	VIL	V _{IH}	V _{IL}	MMM. TOX.COM	See Table 4



Software Command Codes

Command Sequence	1st Bus Write Cycle		2nd Bus Write Cycle		3rd Bus Write Cycle	4th Bus Write Cycle		5th Bus Write Cycle		6th Bus Write Cycle		
	Addr ⁽¹⁾	Data	Addr ⁽¹⁾	Data	Addr ⁽¹⁾	Data	Addr ⁽¹⁾	Data	Addr ⁽¹⁾	Data	Addr ⁽¹⁾	Data
Software Data Protect Enable & Page Write	5555H	AAH	2AAAH	55H	5555H	A0H	Addr ⁽²⁾	Data	CO_{M}	TW TW		
Software Data Protect Disable	5555H	AAH	2AAAH	55H	5555H	80H	5555H	AAH	2AAAH	55H	5555H	20F
Software Chip Erase	5555H	AAH	2AAAH	55H	5555H	80H	5555H	AAH	2AAAH	55H	5555H	10F
Software ID Entry	5555H	AAH	2AAAH	55H	5555H	80H	5555H	AAH	2AAAH	55H	5555H	60H
Software ID Exit	5555H	AAH	2AAAH	55H	5555H	F0H	*XI	MAN	-01.C	$O_{P_{\alpha}}$	TW	

Notes: (1) Address format A₁₄-A₀ (Hex), Addresses A₁₅ and A₁₆ are a "Don't Care".

Notes for Software Product ID Command Code:

WWW.100Y.COM.TW

WWW.100Y.COM

- 1. With A_{14} - A_1 =0; SST Manufacturer Code = BFH, is read with A_0 = 0, 29VE010 Device Code = 07H, is read with $A_0 = 1$.
- 2. The device does not remain in Software Product ID Mode if powered down.

WWW.100Y.COM.TW 勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787 Http://www.100y.com.tw

WWW.100Y.COM.TW

WWW.100Y.COM.TW

⁽²⁾ Page Write consists of loading up to 128 bytes (A - A₀).

勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787 Http://www. 100y. com. tw

SST 29VE010 2.7V-only 1 Megabit Page Mode EEPROM



Absolute Maximum Stress Ratings (Applied conditions greater than those listed under "Absolute Maximum Stress Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these conditions or conditions greater than those defined in the poerational sections of this data sheet is not implied. Exposure to absolute maximum stress rating conditions may affect device reliability.)

Temperature Under Bias	55°C to +125°C
Storage Temperature	65°C to +150°C
D. C. Voltage on Any Pin to Ground Potential	-0.5V to V_{CC} + 0.5V
Transient Voltage (<20 ns) on Any Pin to Ground Potential	-1.0V to V_{CC} + 1.0V
Voltage on A ₉ Pin to Ground Potential	-0.5V to 14.0V
Package Power Dissipation Capability (Ta = 25°C)	1.0W
Through Hole Lead Soldering Temperature (10 Seconds)	300°C
Surface Mount Lead Soldering Temperature (3 Seconds)24	40°C
Output Short Circuit Current	100 mA

Note: (1) Outputs shorted for no more than one second. No more than one output shorted at a time.

Operating Range

Range	Ambient Temp	V _{CC}
Commercial	0 °C to +70 °C	2.7V to 3.6V
Industrial	-40 °C to +85 °C	2.7V to 3.6V

AC Conditions of Test

Input Rise/Fall Time	10 ns
Output Load	1 TTL Gate and C _L = 100 pF
See Figures 13 and 14	

	1100Y.C. TW	M. A.	Limits		11 W 100 1 COM
Symbol Param	Parameter	Min	Max	Units	Test Conditions
Icc	Power Supply Current	- 1	M.I.	"CO	CE#=OE#=V _{IL} ,WE#=V _{IH} , all I/Os open,
	Read		12	mA	Address input = V_{IL}/V_{IH} , at f=1/ T_{RC} Min., $V_{CC}=V_{CC}$ Max
	Write		15	mA	CE#=WE#=V _{IL} , OE#=V _{IH} , V _{CC} =V _{CC} Max.
I _{SB1}	Standby V _{CC} Current (TTL input)		NWW.	mA	CE#=OE#=WE#=V _{IH} , V _{CC} =V _{CC} Max.
I _{SB2}	Standby V _{CC} Current (CMOS input)	N .	15	μА	CE#=OE#=WE#= V_{CC} -0.3V. V_{CC} = V_{CC} Max.
I _{LI}	Input Leakage Current	W	1	μΑ	V_{IN} =GND to V_{CC} , V_{CC} = V_{CC} Max.
I_{LO}	Output Leakage Current	CVV	10	μΑ	V_{OUT} =GND to V_{CC} , V_{CC} = V_{CC} Max.
V _{IL}	Input Low Voltage	-41	0.8	V	V _{CC} = V _{CC} Max.
V_{IH}	Input High Voltage	2.0		V	V _{CC} = V _{CC} Max.
V_{OL}	Output Low Voltage	WT	0.4	VVV	$I_{OL} = 100 \mu A$, $V_{CC} = V_{CC} Min$.
V_{OH}	Output High Voltage	2.4		V	$I_{OH} = -100 \mu A$, $V_{CC} = V_{CC} Min$.
V_H	Supervoltage for A ₉	11.6	12.4	V	CE# = OE# =V _{IL} , WE# = V _{IH}
I _H	Supervoltage Current for A ₉	OM.TY	100	μΑ	$CE\# = OE\# = V_{IL}$, $WE\# = V_{IH}$, $A_9 = V_H$ Max.



Table 6: Power-up Timings

Symbol	Parameter	Maximum	Units
T _{PU-READ} (1)	Power-up to Read Operation	100	μs
T _{PU-WRITE} (1)	Power-up to Write Operation	5	ms

Table 7: Capacitance (Ta = 25 °C, f=1 Mhz, other pins open)

Parameter	Description	Test Condition	Maximum
C _{I/O} ⁽¹⁾	I/O Pin Capacitance	$V_{I/O} = 0V$	12 pF
C _{IN} ⁽¹⁾ Input Capacitano		$V_{IN} = 0v$	6 pF

Note: ⁽¹⁾This parameter is measured only for initial qualification and after a design or process change that could affect this parameter.

Table 8: Reliability Characteristics

Symbol	Parameter	Minimum Specification	Units	Test Method
N _{END}	Endurance	1,000 & 10,000 ⁽²⁾	Cycles	MIL-STD-883, Method 1033
T _{DR} ⁽¹⁾	Data Retention	100	Years	MIL-STD-883, Method 1008
V _{ZAP_HBM} (1)	ESD Susceptibility Human Body Model	1000	Volts	JEDEC Stadard A114
$V_{ZAP_MM}^{(1)}$	ESD Susceptibility Machine Model	200	Volts	JEDEC COM
I _{LTH} ⁽¹⁾	Latch Up	100	mA	JEDEC Standard 17

Note: ⁽¹⁾This parameter is measured only for initial qualification and after a design or process change that could affect this parameter.

⁽²⁾ See Ordering Information for desired type.



AC Characteristics

Table 9: **Read Cycle Timing Parameters**

Symbol	Parameter	29VE010-200		29VE010-250		O_{M} .
		Min	Max	Min	Max	Units
T _{RC}	Read Cycle time	200		250	100Y.	ns
ГСЕ	Chip Enable Access Time	O_{Mr}	200	WW	250	ns
AA	Address Access Time	OW	200		250	ns
T _{OE}	Output Enable Access Time	OM	100		120	ns
$\Gamma_{\rm CLZ}^{(1)}$	CE# Low to Active Output	0	WT	0	110	ns
OLZ (1)	OE# Low to Active Output	(O)	TW	0 <	MM	ns
Г _{СНZ} ⁽¹⁾	CE# High to High-Z Output	-1 CO1	50		50	ns
- (1) OHZ	OE# High to High-Z Output	07.0	50		50	ns
OH ⁽¹⁾	Output Hold from Address Change	00.0	OM.TW	0	MM	ns

Table 10: Page-Write Cycle Timing Parameters

Symbol	Parameter	Min	Max	Units
T _{WC}	Write Cycle (erase and program)	N.C.	10	ms
T _{AS}	Address Setup Time	0	VTT	ns
T _{AH}	Address Hold Time	50)Mr.	ns
T _{CS}	WE# and CE# Setup Time	0	OM_{IJ}	ns
T _{CH}	WE# and CE# Hold Time	0	.M.	ns
T _{OES}	OE# High Setup Time	0	COn	ns
T _{OEH}	OE# High Hold Time	0	$^{1}CO_{\tilde{M}_{1}}$	ns
T _{CP}	CE# Pulse Width	70	- cO1	ns
T_{WP}	WE# Pulse Width	70	N.C.	ns
T _{DS}	Data Setup Time	35	MY.CL	ns
T_{DH}	Data Hold Time	0	- N.C	ns
T _{BLC} ⁽¹⁾	Byte Load Cycle Time	0.05	100	μs
$T_{\text{BLCO}}^{(1)}$	Byte Load Cycle Time	200	700X	μs
T_IDA	Software ID Access and Exit Time	MMA	10	μs
T_{SCE}	Software Chip Erase	WW	20	ms

Note: (1) This parameter is measured only for initial qualification and after the design or process change that could affect this parameter.

> 料 886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787

Http://www. 100y. com. tw



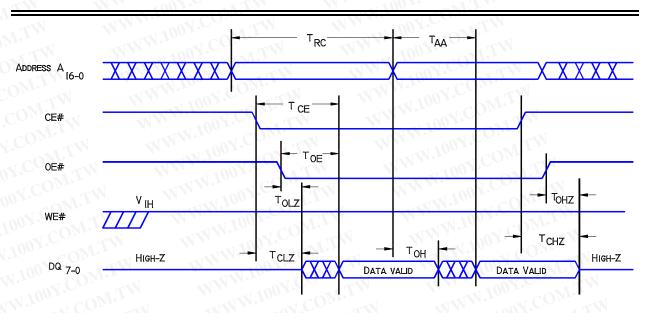


Figure 3: Read Cycle Timing Diagram

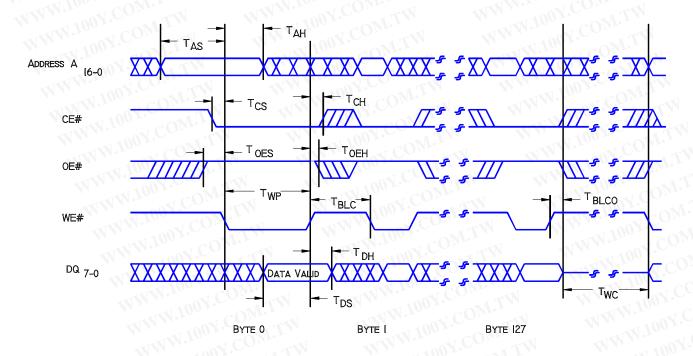


Figure 4: WE# Controlled Page Write Cycle Timing Diagram



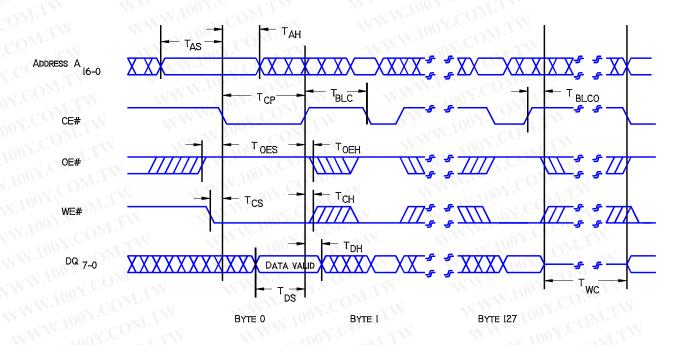


Figure 5: CE# Controlled Page Write Cycle Timing Diagram

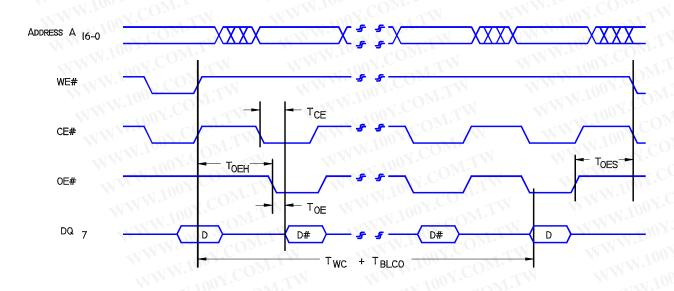


Figure 6: Data# Polling Timing Diagram



勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787

Http://www.100y.com.tw

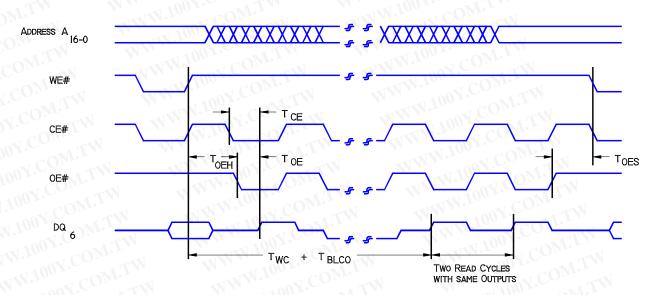
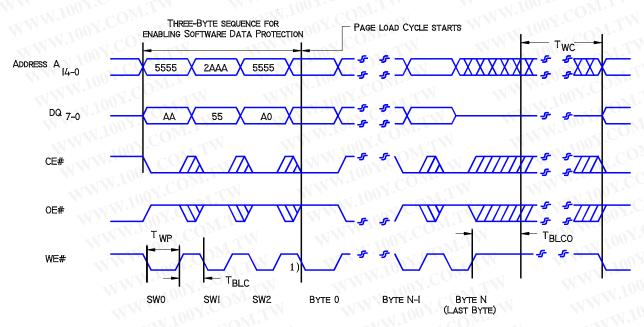


Figure 7: Toggle Bit Timing Diagram

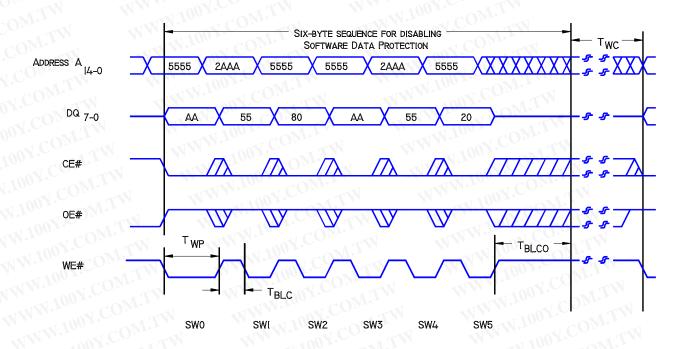


NOTE I): THE TIME BETWEEN ENABLING SOFTWARE DATA PROTECT AND THE PAGE LOAD MUST BE LESS THAN T BLCO

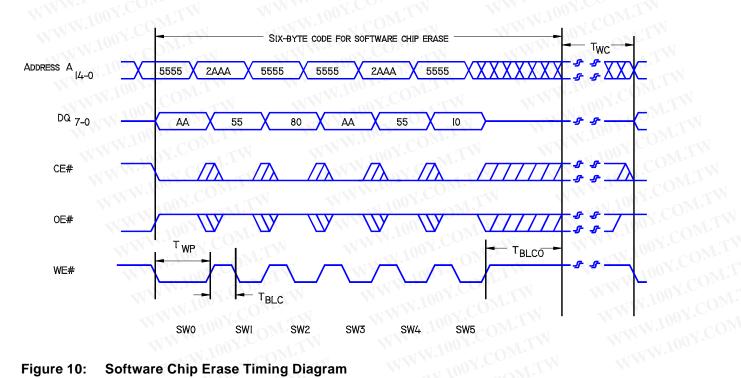
Figure 8: Software Data Protection Page Write Timing Diagram

勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787 Http://www. 100y. com. tw





Software Data Protect Disable Timing Diagram



Software Chip Erase Timing Diagram Figure 10:



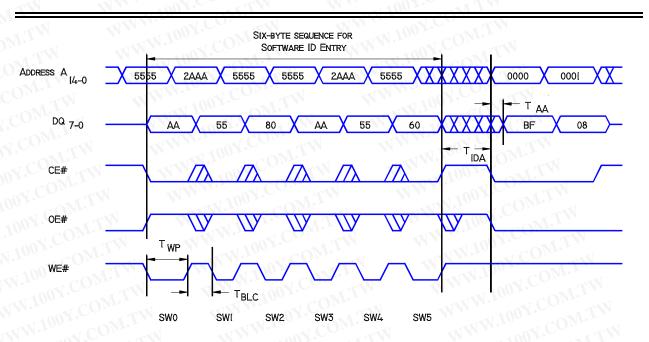


Figure 11: Software ID Entry and Read

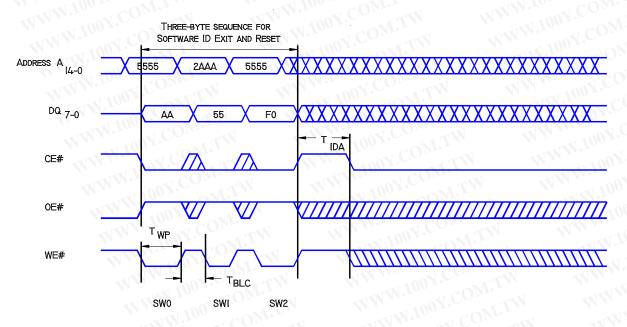


Figure 12: Software ID Exit and Reset





AC test inputs are driven at V_{OH} (2.4 V_{TTL}) for a logic "1" and V_{OL} (0.4 V_{TTL}) for a logic "0". Measurement reference points for inputs and outputs are V_H (2.0 V_{TTL}) and V_{IL} (0.8 V_{TTL}). Inputs rise and fall times (10% \leftrightarrow 90%) are <10 ns.

Figure 13: AC Input/Output Reference Waveforms

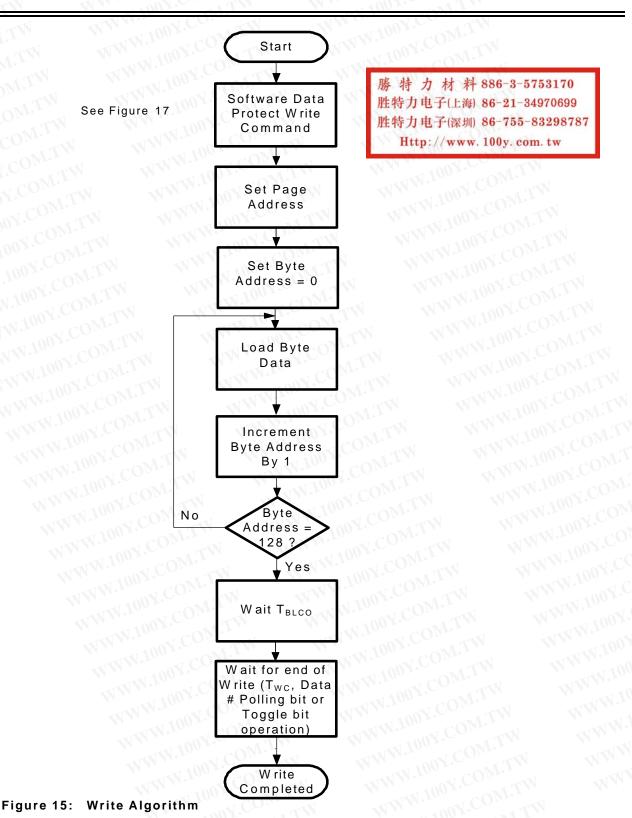
勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787 Http://www.100y.com.tw

TO DUT TO DUT TO TESTER TO TESTER R_L HIGH

Figure 14: Test Load Example



W.100Y.COM.TW





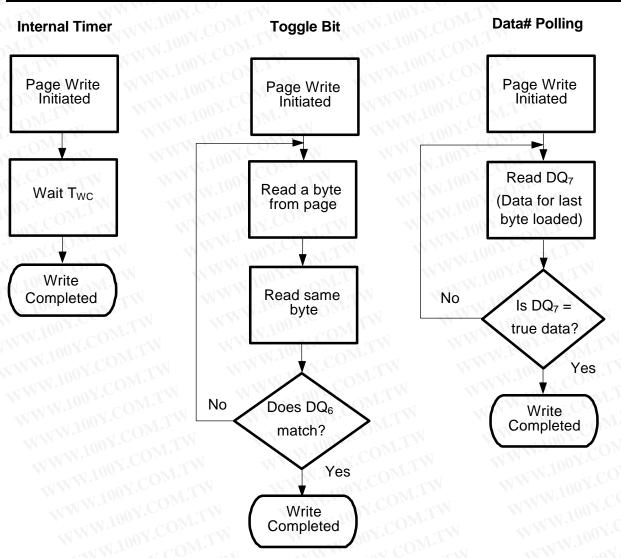
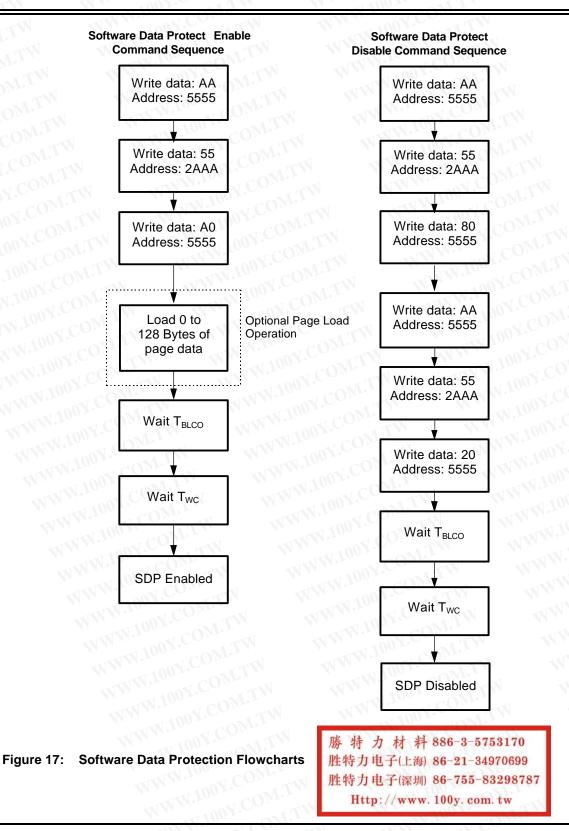


Figure 16: Wait Options

WWW.100Y.COM.TW







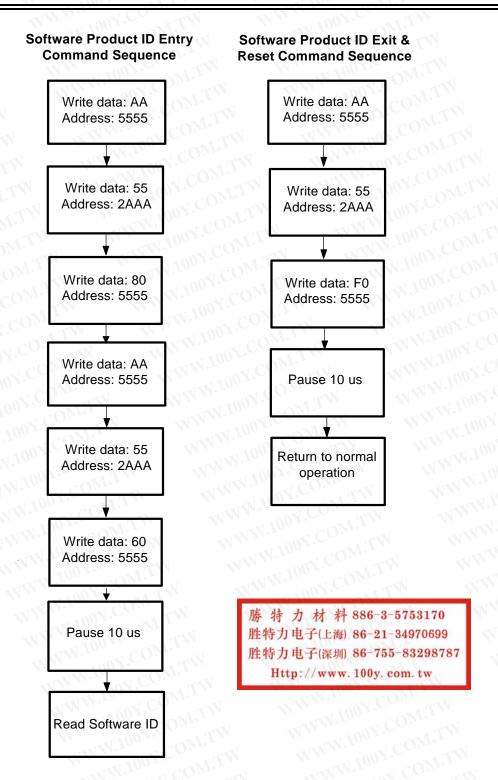


Figure 18: Software Product Command Flowcharts



WWW.100X

W.100Y.COM.TV

SST 29VE010 2.7V-only 1 Megabit Page Mode EEPROM

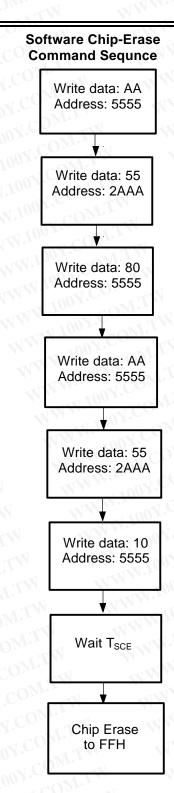


Figure 19: Software Chip Erase Command Codes

W.100Y.COM.TW

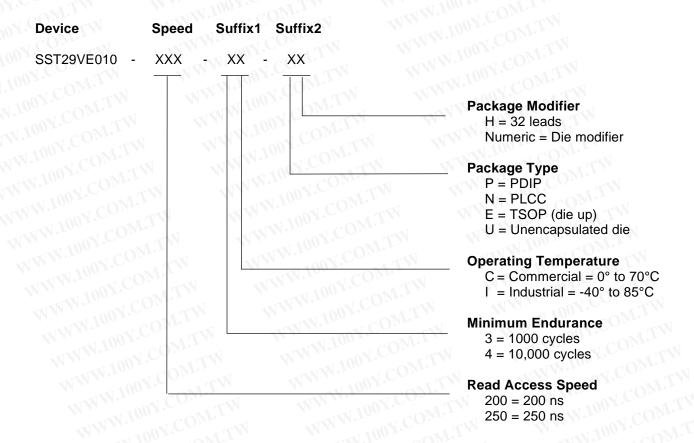
特力材料886-3-5753170

胜特力电子(深圳) 86-755-83298787 Http://www.100y.com.tw

胜特力电子(上海) 86-21-34970699



Product Ordering Information





Valid combinations

N.100Y.C	Valid combinations		
M.100X	SST29VE010-200-4C- EH SST29VE010-250-4C- EH	SST29VE010-200-4C- NH SST29VE010-250-4C- NH	SST29VE010-200-4C- PH SST29VE010-250-4C- PH
AMM.100.	SST29VE010-200-3C- EH SST29VE010-250-3C- EH	SST29VE010-200-3C- NH SST29VE010-250-3C- NH	SST29VE010-200-3C- PH SST29VE010-250-3C- PH
WWW.1	SST29VE010-200-4I-EH SST29VE010-250-4I-EH	SST29VE010-200-4I-NH SST29VE010-250-4I-NH	SST29VE010-250-4C-U1
MMA	SST29VE010-200-3I-EH SST29VE010-250-3I-EH	SST29VE010-200-3I-NH SST29VE010-250-3I-NH	SST29VE010-250-3C-UI
WW			

WWW.100Y.C Example: Valid combinations are those products in mass production or will be in mass production. Consult your SST sales re presentative to confirm availability of valid combinations and to determine availability of new combin ations. WWW.100Y.COM.TW

> 勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787 Http://www. 100y. com. tw

WWW.100Y.COM.TW